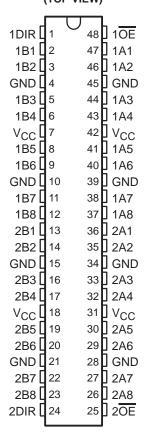
SN54ABTH162245, SN74ABTH162245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCBS712A - FEBRUARY 1998 - REVISED APRIL 1999

- **Members of the Texas Instruments** Widebus™ Family
- A-Port Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic Thin** Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

SN54ABTH162245 . . . WD PACKAGE SN74ABTH162245 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



description

The 'ABTH162245 devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent $25-\Omega$ series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH162245 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABTH162245 is characterized for operation from -40°C to 85°C.



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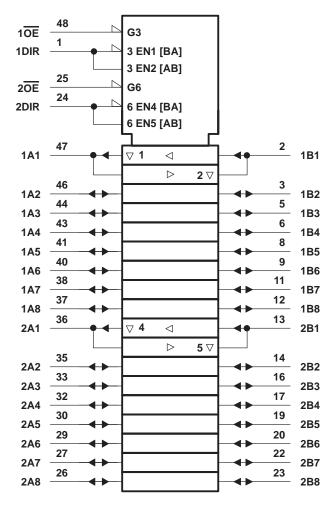


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FUNCTION TABLE (each 8-bit section)

INP	UTS	ODED ATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

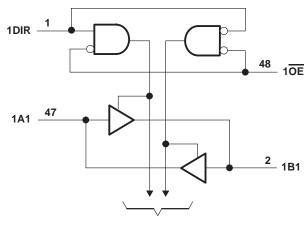
logic symbol†

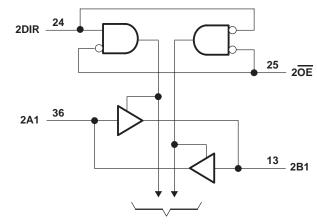


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





To Seven Other Channels

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, V _O	. −0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABTH162245 (B port)	96 mA
SN74ABTH162245 (B port)	
SN54/74ABTH162245 (A port)	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} ($V_O < 0$)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	89°C/W
DGV package	93°C/W
DL package	94°C/W
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 3)

			SN54ABTH	162245	SN74ABTH	1162245	LINIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	4	2		V
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	√Vcc	0	VCC	V	
lau	High lovel output current	B port	2	-24		-32	mA
ЮН	High-level output current	A port	5	-12		-12	IIIA
lo:	Low-level output current	B port	90	48		64	mA
IOL	Low-level output current	A port	Q Q	12		12	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			ABTH16	2245	SN74ABTH162245			UNIT	
		LEST CONDITION	NS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 5 V$,	$I_{OH} = -1 \text{ mA}$	2.5			2.5				
	A port		$I_{OH} = -1 \text{ mA}$	3			3				
	A poit	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	3			3.1				
Vон			$I_{OH} = -12 \text{ mA}$				2.6			V	
VОН		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3			V	
	B port		$I_{OH} = -3 \text{ mA}$	2.5			2.5				
	D poit	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2							
			$I_{OH} = -32 \text{ mA}$				2				
	A port		I_{OL} = 12 mA			8.0			0.8		
VOL	B port	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.45			0.45	V	
	D port		$I_{OL} = 64 \text{ mA}$						0.55		
V_{hys}					100	E. C.		100		mV	
IĮ	Control inputs	$V_{CC} = 5.5 \text{ V}, V_{I} = V_{CC} \text{ or GND}$			BAEL	±1			±1	μΑ	
	A or B ports				6	±20			±20		
ha in		V _{CC} = 4.5 V	V _I = 0.8 V	100	3		100				
l(hold)		VCC = 4.5 V	V _I = 2 V	-100)		-100			μΑ	
l _{off}		$V_{CC} = 0,$ $V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$		Q					±100	μΑ	
lo‡	A port	V _{CC} = 5.5 V,	V _O = 2.5 V	-25		-90	-25		-100	mA	
10+	B port	VCC = 5.5 V,	V() = 2.5 V	-50		-180	-50		-180	IIIA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50			50	μΑ	
		V _{CC} = 5.5 V,	Outputs high			2			2		
Icc	A or B ports	$I_{O} = 0$,	Outputs low			32			32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2			2		
∆lcc§	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				2			2	mA	
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5			1.5		
Ci		V _I = 2.5 V or 0.5 V			3			3		pF	
C _{io}		V _O = 2.5 V or 0.5 V			6			6		рF	

 $[\]uparrow$ All typical values are at $V_{CC} = 5 \text{ V}$.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

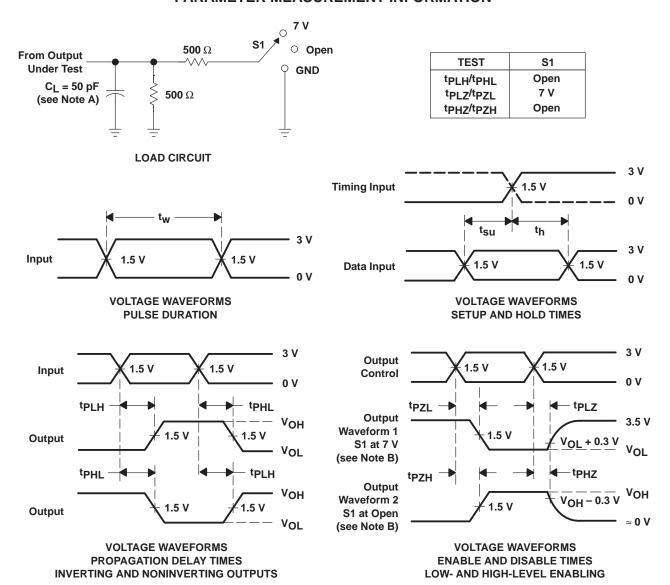
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABTH	1162245	SN74ABTH	UNIT	
	(1141 01)	(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	В	1	2.2	3.4	1	4.1	1	3.9	ns
^t PHL	1 ^	Ь	1	2.3	3.7	1	4.4	1	4.2	115
^t PLH	В	_	1	2.7	4.1	1	4.9	1	4.6	no
^t PHL]	A	1.5	3.1	4.6	1.5	5.2	1.5	5.1	ns
^t PZH		В	1	3.6	5.2	1 /	6.4	1	6.3	ns
t _{PZL}	ŌĒ	В	1	3.7	5.4	1/	6.5	1	6.4	115
^t PHZ	ŌĒ	Б	2	4.4	5.8	2	6.4	2	6.3	
^t PLZ		В	1.5	3.3	4.7	9.5	5.6	1.5	5.2	ns
^t PZH		Α	1.5	4.1	6	1.5	7.2	1.5	7.1	
^t PZL	ŌĒ	Α	1.5	4.3	6.1	1.5	7.3	1.5	7	ns
^t PHZ	ŌĒ	Δ.	2	4.5	6.1	2	6.8	2	6.6	
^t PLZ	1 0	А	1.5	3.7	5.1	1.5	6.1	1.5	5.7	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABTH162245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH162245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH162245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH162245DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTH162245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH162245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH162245DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTH162245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

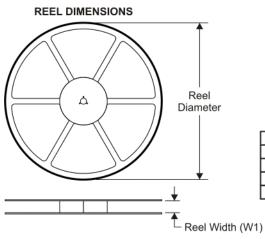
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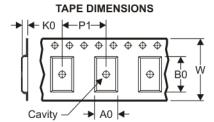
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PACKAGE MATERIALS INFORMATION

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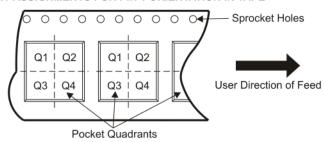
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTH162245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABTH162245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTH162245DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ABTH162245DGVR	TVSOP	DGV	48	2000	346.0	346.0	33.0

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